EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	58	emesh.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:12
S2	40	emesh.in. and polishing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:14
S6	2	10/826219	US-PGPUB; USPAT	OR	ON	2007/03/15 17:33
S4	1	"6497800".pn.	US-PGPUB; USPAT	OR	ON	2007/03/15 17:33
S3	41	("20020102853"|"3328273"|"4430173"|"4948474"|"4954142"|"4975159"|"5084071"|"5256565"|"5354490"|"5472592"|"5516412"|"5681215"|"5755859"|"5762544"|"5770095"|"5773364"|"5793272"|"5795215"|"5807165"|"5840629"|"5858813"|"5884990"|"5897375"|"5911619"|"5922091"|"5930699"|"5933753"|"5954997"|"5985123"|"6004880"|"6027631"|"6063506"|"6066030"|"6071388"|"6074544"|"6103085"|"6132587"|"6136163"|"6176992"|"6270646"|"6537144").PN.	US-PGPUB; USPAT	OR	ON	2007/03/15 17:43
S7	15458	(electropolishing polishing planarization planariz$3 etching electroetching) and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:46
S8	776	S7 and (electrode cathode contact finger pin) with (promixity proximat$3 (without "not") near2 (touch$3 contact$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:48
S9	12261	S7 and (wafer workpiece substrate microelectronic micropiece wsid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:49

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S11	431	S10 and @pn>"2002"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:52
S10	689	S8 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:55
S12	362	S10 and (contact finger pin) near2 (electrical current voltage)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/15 17:58
S5	1	10/826218	US-PGPUB; USPAT	OR	ON	2007/03/16 10:50
S13	105	S10 and (contact finger pin) near2 (electrical current voltage) same (electrode cathode contact finger pin) with (promixity proximat$3 (without "not") near2 (touch$3 contact$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/16 11:34
S16	2	"6106680".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/16 12:07
S17	2	"6251235".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/16 12:11
S14	76	205/147.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/16 12:11
S18	2	"6143155".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:37

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S20	1	205/147.ccls. and (polish$3 electropolish$3 planariz$3 planarization) and abrasive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:38
S15	14	205/147.ccls. and (polish$3 electropolish$3 planariz$3 planarization)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:38
S19	1039	(electropolishing planarization) and (wafer semiconductor microelectronics micropiece) and ("204" "205") and pad with abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:39
S22	116	(electropolishing planarization) and (wafer semiconductor microelectronics micropiece) and ("204" "205").clas. and pad near3 abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:40
S21	662	(electropolishing planarization) and (wafer semiconductor microelectronics micropiece) and ("204" "205") and pad near3 abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/19 18:40
L1	433	Homayoun near2 talieh cyprian near2 uzoh bulent near2 basol "nutool.as" nu adj tool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 12:47
L2	69	1 and (proximate proximity without near3 (touching contacting)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 12:51
L3	2	1 and (without near3 (touching contacting)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 12:52

L5	2	"6413388".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 12:57
L4	26	1 and (without near3 (touching contacting))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/20 12:57